# H6089 Qseven module with Intel® Atom® SOC



The H6089 is a compact (70mm x 70mm) high-performance, low power COM module based on the Intel® Atom® Elkhart Lake Systemon-Chip. The SOC have the 11<sup>th</sup> generation Intel® UHD Graphics Engine GPU built in along with a dual or quad core CPU and I/O controller.

The Oseven form factor makes H6089 a module with a full range of low voltage differential serial interfaces such as PCI Express, USB 3.1, SATA and display interfaces such as DisplayPort or HDMI and Dual 24-bit LVDS. Qseven modules are defined for low cost and ruggedness, with an MXM type edgecard connector interfacing the carrier board. H6089 has soldered memory and optional on-board eMMC Flash. The H6089 is available in both standard and industrial grade operating temperature.



### **FEATURES**

- Dual or Quad core Intel® Atom® SOC
- 11th generation Intel® UHD Graphics Engine
- Industrial temperature range (-40°C to +85°C)
- Up to three USB 3.1 or up to eight USB 2.0
- First Atom® CPU with support for Windows 11
- Optional on-board eMMC Flash storage
- Soldered LPDDR4x RAM memory
- Dual 24-bit LVDS and DisplayPort/HDMI
- Compatible with Q7 revision 2.1

## LOOKING FOR SOMETHING SLIGHTLY DIFFERENT?

to specification. With small modifications to hardwa- changes in standard products to meet your requirere and software, you can have the qualities and func- ments exactly. tions you need.

In most cases standard products can be customized Call us. We will be happy to suggest and implement



# ENABLING YOUR NEXT STEP

# H6089 - Technical Specifications

#### SOC (CPU+GPU+I/O)

Intel Atom® x6211E, 1.3 GHz DC, Q7 board, 4 GiB RAM, no eMMC, 1 USB3, 8 USB2, no fan/temp, industrial temp

Intel Atom® x6413E, 1.5 GHz QC, Q7 board, 8 GiB. 16 GB eMMC, 1 USB3, 8 USB2, industrial temp

Intel Atom® x6425E, 2.0 GHz QC, Q7 board, 16 GiB, 16 GB eMMC, 3 USB3, 4 USB2, industrial temp

INTEGRATED GRAPHICS

Integrated 2D/3D/MPEG hardware acceleration

GPU: 11th generation Intel® UHD Graphics Engine

MEMORY

Soldered LPDDR4x RAM, 2GiB, 4GiB, 8GiB or 16GiB

ONBOARD FLAH STORAGE (OPTIONAL)

eMMC, up to 128 GB, configurable as TLC or pSLC

#### SATA

2 x SATA Gen 3 ports

BATTERY MANAGEMENT

Support for Smart battery implementation on carrier board

POWER MANAGEMENT

ACPI 5.0 compliant Support for S3 and S4

SERIAL PORT

1 x COM (Tx, Rx, RTS, CTS)

BIOS Support for Super I/O on Carrier Board

CAN BUS

1 CAN (Supporting both CAN 2.0 and CAN FD)

SD Card

1 x SD Card port

USB

One of the following configurations:

a) 1 x USB 3.1 and 8 x USB 2.0

b) 2 x USB 3.1 and 6 x USB 2.0

c) 3 x USB 3.1 and 4 x USB 2.0

PCIE PORTS

4 x PCle x1 Gen 3

LPC BUS

1 x LPC

ETHERNET

Intel® Gigabit Ethernet

SERIAL INTERFACE

I2C/SMBus interface

BIOS

AMI Aptio® V UEFI BIOS

DISPLAY INTERFACE

Dual 24-bit LVDS and DisplayPort/HDMI

AUDIO

Support for HDA audio codec on carrier board

POWER

+5V +/-5%

OPERATING TEMPERATURE

Standard: 0°C to +60°C

Industrial: -40°C to +85°C

HUMIDITY

10 to 90% (operating)

5 to 95% (storage)

FORM FACTOR

Qseven Specification 2.1, 70mm x 70mm

**OPTIONAL ACESSORIES** 

Q7 Evaluation Carrier Board

Heatspreader

Heatsink

**Coating Service** 

**BIOS Customization Service** 

VISITORS ADDRESS: Åkaregatan 2 Uppsala TELEPHONE: +46 18 660 700 TELEFAX: +46 18 660 701 E-MAIL: info@hectronic.se

